MOSFET - Power, Single N-Channel, SO8-FL 30 V, 1.74 mΩ, 170 A

NTMFS1D7N03CG

Features

- Wide SOA to Improve Inrush Current Management
- Advanced Package (5x6 mm) with Excellent Thermal Conduction
- Ultra Low R_{DS(on)} to Improve System Efficiency
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Hot Swap Application
- Power Load Switch
- Battery Management and Protection

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	30	V
Gate-to-Source Voltage			V _{GS}	±20	V
Continuous Drain		T _C = 25°C	I _D	170	Α
Current R _{0JC} (Note 2)	Steady	T _C = 100°C		120	
Power Dissipation R _{θJC} (Note 2)	State	T _C = 25°C	P _D	87	W
Continuous Drain Current R _{0JA} (Note 1)	Steady State	T _A = 25°C	I _D	35	Α
		T _A = 100°C	1	25	
Power Dissipation $R_{\theta JA}$		T _A = 25°C	P _D	3.8	W
Pulsed Drain Current	T _A = 25	°C, t _p = 10 μs	I _{DM}	900	Α
Source Current (Body Diode)			IS	73	Α
Single Pulse Drain-to-Source Avalanche Energy I _L = 50.6 A _{pk}			E _{AS}	128	mJ
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface-mounted on FR4 board using a 1 in², 2 oz. Cu pad.

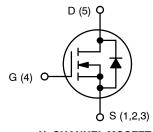
- 2. The entire application environment impacts the thermal resistance values shown. They are not constants and are only valid for the particular conditions noted. Actual continuous current will be limited by thermal & electro-mechanical application board design. $R_{\theta CA}$ is determined by the user's board design.



ON Semiconductor®

www.onsemi.com

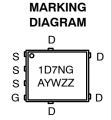
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
30 V	1.74 mΩ @ 10 V	170 A	



N-CHANNEL MOSFET



(SO-8FL) CASE 488AA STYLE 1



1D7NG = Specific Device Code = Assembly Location

= Year W = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 1)	$R_{ heta JC}$	1.73	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{ heta JA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS						•	•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J	I _D = 250 μA, ref to 25°C			16		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V}, \qquad T_{J} = 25^{\circ}\text{C}$			1.0	μΑ	
	$V_{DS} = 30 \text{ V}$ $T_{J} = 125^{\circ}$	T _J = 125°C			100		
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V				100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 90 \mu A$		1.3		2.2	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J	I _D = 90 μA, ref to 25°C			-5.1		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 18 A			1.45	1.74	mΩ
Forward Transconductance	9 _{FS}	V _{DS} = 5 V, I _D = 18 A			46		
Gate Resistance	R_{G}	T _A = 25°C			0.8		Ω
CHARGES & CAPACITANCES						•	•
Input Capacitance	C _{ISS}	V _{GS} = 0 V, V _{DS} = 15 V, f = 1 MHz			3780		pF
Output Capacitance	C _{OSS}				1770		
Reverse Capacitance	C _{RSS}				50		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 15 V; I _D = 18 A			48		nC
Threshold Gate Charge	Q _{G(TH)}				7		
Gate-to-Source Charge	Q _{GS}				12		
Gate-to-Drain Charge	Q_{GD}				3		
SWITCHING CHARACTERISTICS, V _{GS} =	10 V						
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DS} = 15 V, I_{D} = 18 A, R_{G} = 3 Ω			16		ns ns
Rise Time	t _r				6		
Turn-Off Delay Time	t _{d(OFF)}				39		
Fall Time	t _f				6		
DRAIN-SOURCE DIODE CHARACTERIS	TICS						
Forward Diode Voltage	V_{SD}	43 - 17	T _J = 25°C		0.78	1.2	.,
			T _J = 125°C		0.63		·
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, V _R = 15 V, I _S = 18 A,			55		ns
Reverse Recovery Charge	Q _{RR}	dl/dt = 100			45		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width $\leq 300 \,\mu\text{s}$, duty cycle $\leq 2\%$.

^{4.} Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

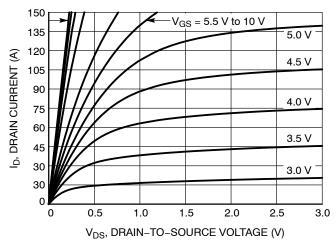


Figure 1. On-Region Characteristics

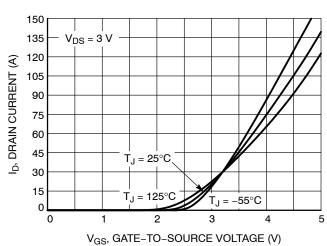


Figure 2. Transfer Characteristics

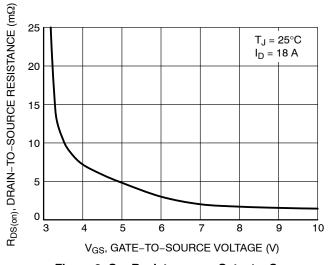


Figure 3. On-Resistance vs. Gate-to-Source Voltage

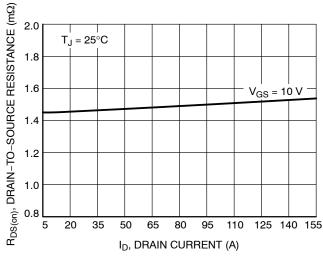


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

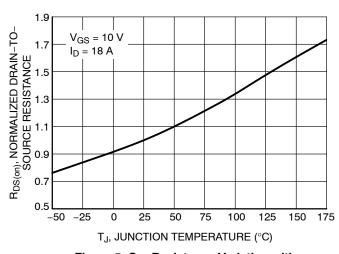


Figure 5. On–Resistance Variation with Temperature

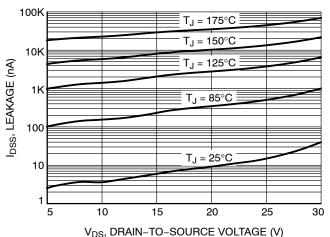


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

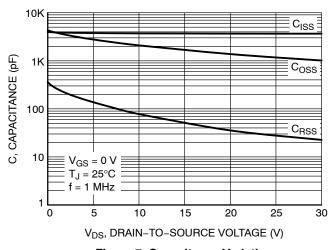


Figure 7. Capacitance Variation

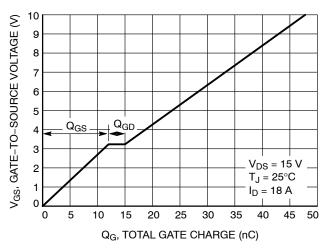


Figure 8. Gate-to-Source Voltage vs. Total Charge

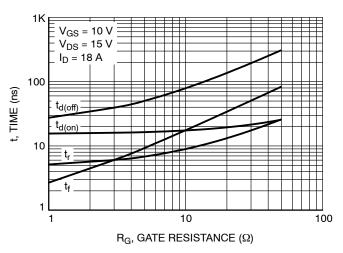


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

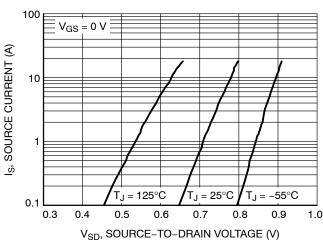


Figure 10. Diode Forward Voltage vs. Current

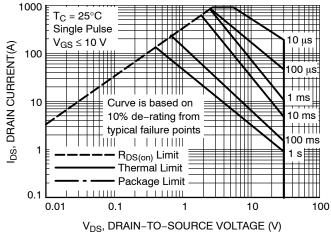


Figure 11. Maximum Rated Forward Biased Safe Operating Area

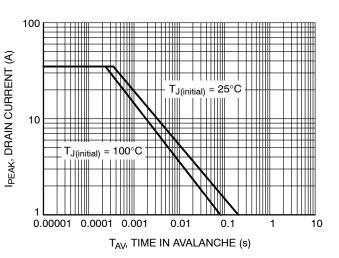


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS

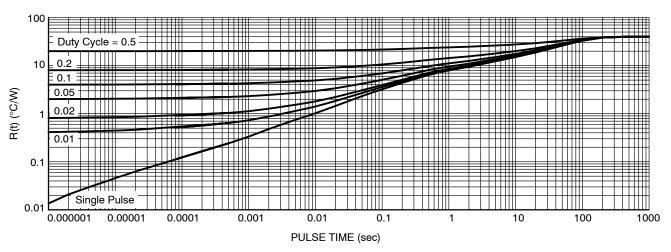


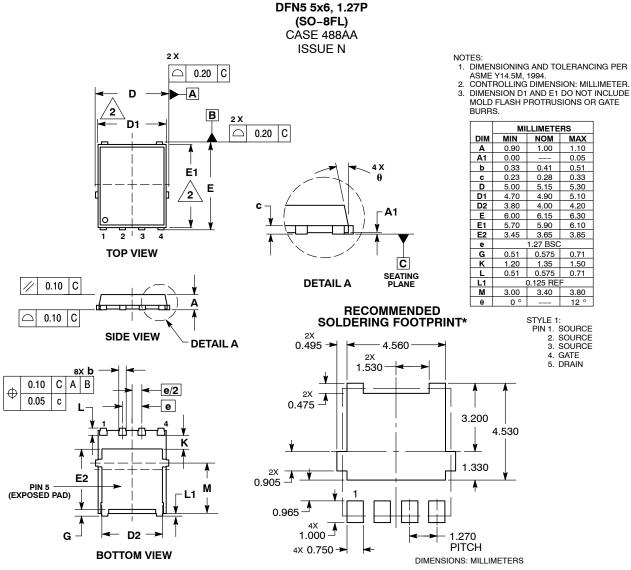
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS1D7N03CGT1G	1D7NG	DFN5 (Pb-Free)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 🕠 are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability. arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910

ON Semiconductor Website: www.onsemi.com

Phone: 011 421 33 790 2910